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M s e m i t e k

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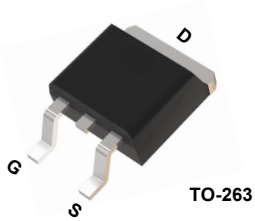
SLB150N06G
60V N-Channel MOSFET

General Description

This Power MOSFET is produced using Msemitek's advanced Shielding Gate MOSFET technology.
This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as DC/DC converters and high efficiency switching for power management in portable and battery operated products.

Features

- 150A, 60V, $R_{DS(on)Typ}$ = 2.4mΩ@V_{GS} = 10 V
- Very Low On-resistance $R_{DS(ON)}$
- High ruggedness
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



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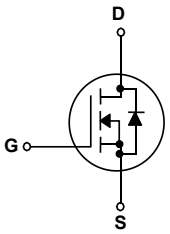


Absolute Maximum Ratings

T_C = 25°C unless otherwise noted

Symbol	Parameter		SLB150N06G	Units
V_{DSS}	Drain-Source Voltage		60	V
I_D	Drain Current - Continuous (T_C = 25℃)		150	A
	- Continuous (T_C = 100℃)		98	A
I_{DM}	Drain Current - Pulsed	(Note 1)	450	A
V_{GSS}	Gate-Source Voltage		±20	V
EAS	Single Pulsed Avalanche Energy	(Note 2)	552	mJ
E_{AR}	Repetitive Avalanche Energy	(Note 1)	240	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P_D	Power Dissipation (T_C = 25℃)		192	W
	- Derate above 25℃		1.54	W/℃
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	℃
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	℃

* Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	SLB150N06G	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.65	℃/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	℃/W

Package Marking

Part Number	Top Marking	Package	Packing Method	MOQ	QTY
SLB150N06G	SLB150N06G	TO-263	Tape & Reel	800	4000

Electrical Characteristics

T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = 250 uA	60	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 60 V, V_{GS} = 0 V	--	--	1	uA
		V_{DS} = 48 V, T_C = 150℃	--	--	10	uA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = 20V, V_{DS} = 0 V	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -20 V, V_{DS} = 0 V	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250 uA	1.0	--	2.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = 10 V, I_D = 30 A	--	2.4	2.8	mΩ
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 25 V, V_{GS} = 0 V, f = 1.0 MHz	--	5460	--	pF
C_{oss}	Output Capacitance		--	2040	--	pF
C_{rss}	Reverse Transfer Capacitance		--	5.5	--	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 30 V, I_D = 60 A, R_G = 4.7 Ω (Note 4, 5)	--	20	--	ns
t_r	Turn-On Rise Time		--	127	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	95	--	ns
t_f	Turn-Off Fall Time		--	25	--	ns
Q_g	Total Gate Charge	V_{DS} = 30 V, I_D =30 A, V_{GS} = 10 V (Note 4, 5)	--	70	--	nC
Q_{gs}	Gate-Source Charge		--	21	--	nC
Q_{gd}	Gate-Drain Charge		--	33	--	nC
R_G	Gate Resistance	f = 1MHz	--	1.8	--	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	150	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	450	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = 30 A	--	--	1.4	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0 V, I_S =30 A, dI_F / dt = 80 A/us (Note 4)	--	63	--	ns
Q_{rr}	Reverse Recovery Charge		--	59	--	nC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. I_{AS} =I_D, V_{DD} =30V, R_G = 25Ω, Starting T_J = 25°C
3. I_{SD} ≤ I_D, di/dt ≤ 200A/us, V_{DD} ≤ $BV_{DSS,}$ Starting T_J = 25°C
4. Pulse Test : Pulse width ≤ 300us, Duty cycle ≤ 2%
5. Essentially independent of operating temperature

N- Channel Typical Characteristics

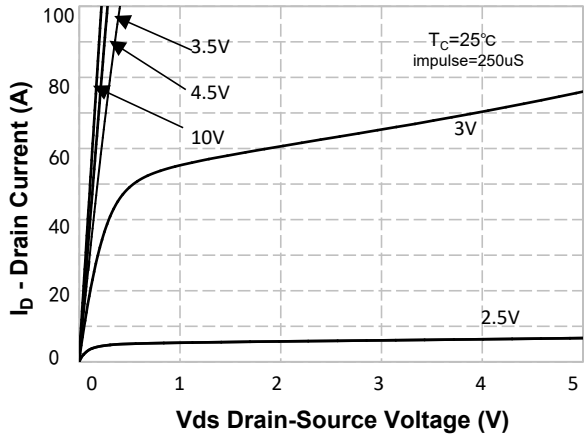


Figure 1. On-Region Characteristics

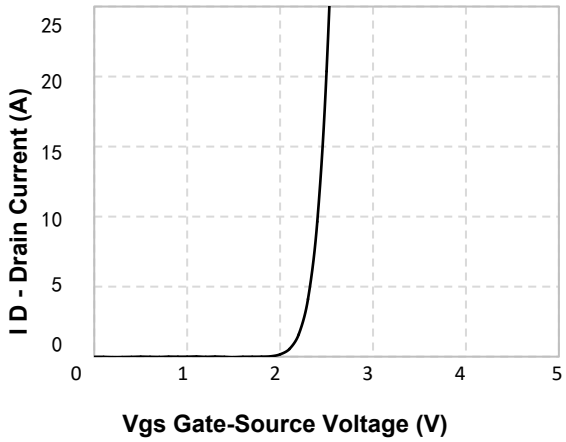


Figure 2. Transfer Characteristics

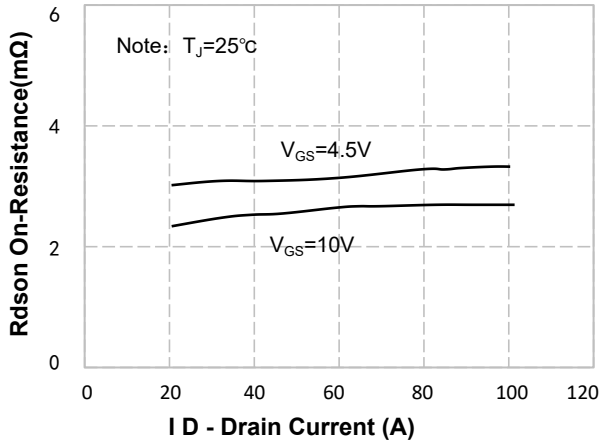


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

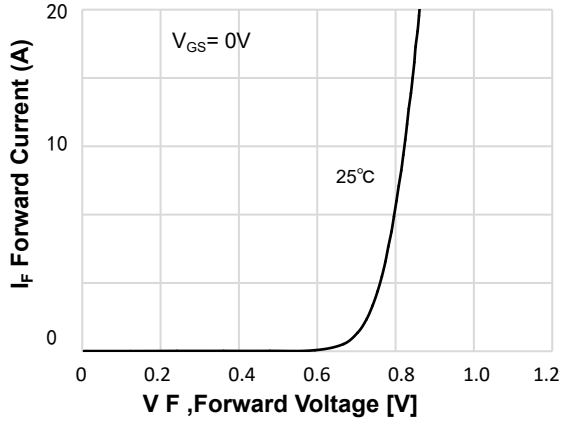


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

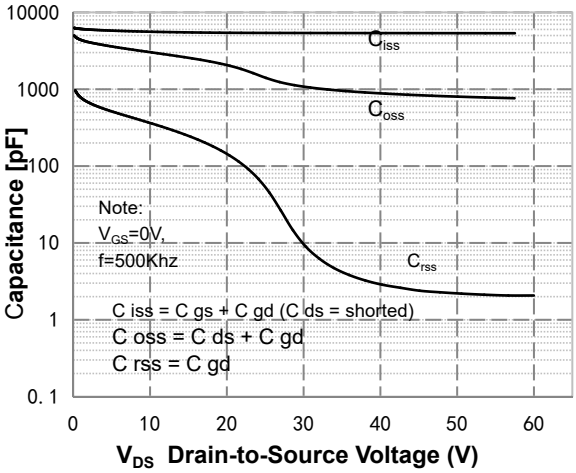


Figure 5. Capacitance Characteristics

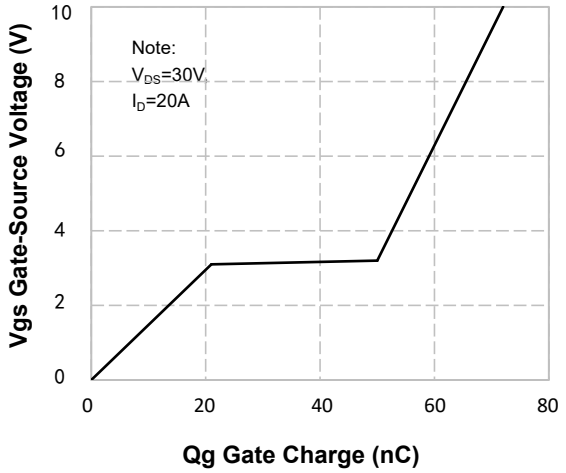


Figure 6. Gate Charge Characteristics

N- Channel Typical Characteristics (Continued)

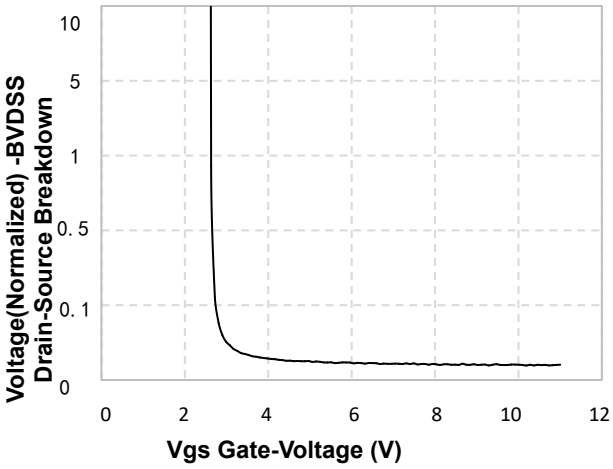


Figure 7. Breakdown Voltage Variation vs Gate-Voltage

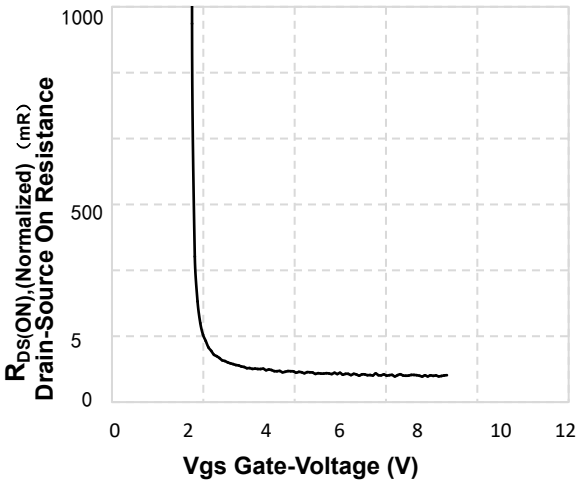


Figure 8. On-Resistance Variation vs Gate Voltage

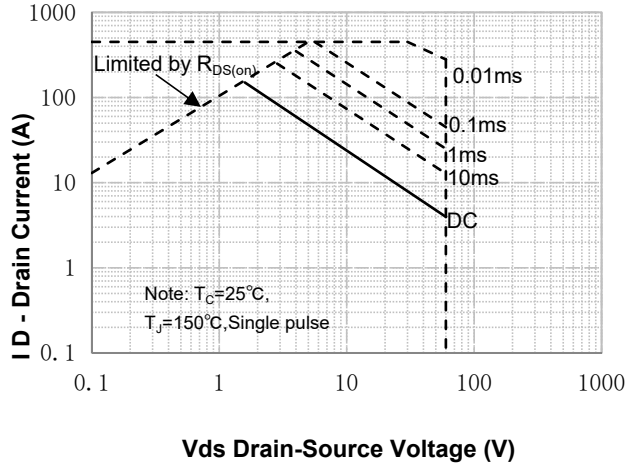


Figure 9. Maximum Safe Operating Area

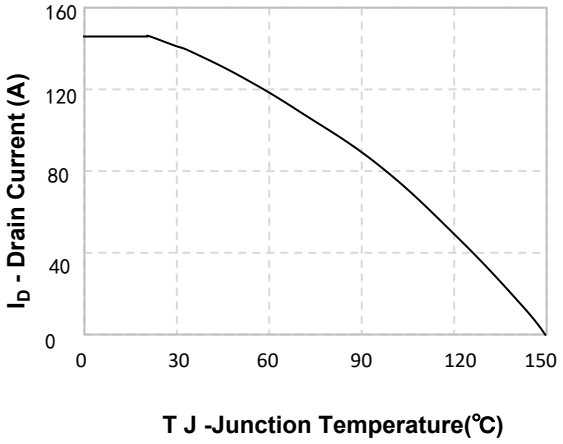


Figure 10. Maximum Continuous Drain Current vs Temperature

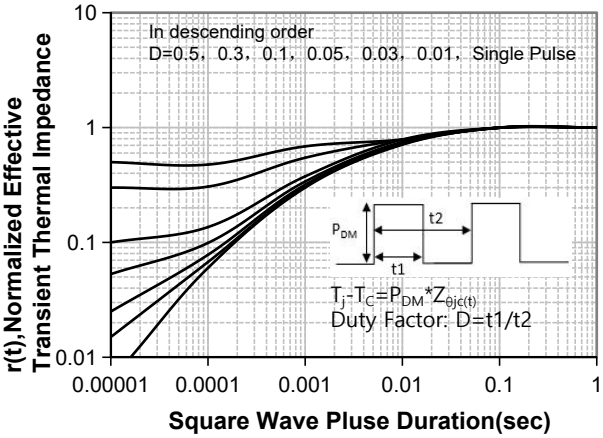
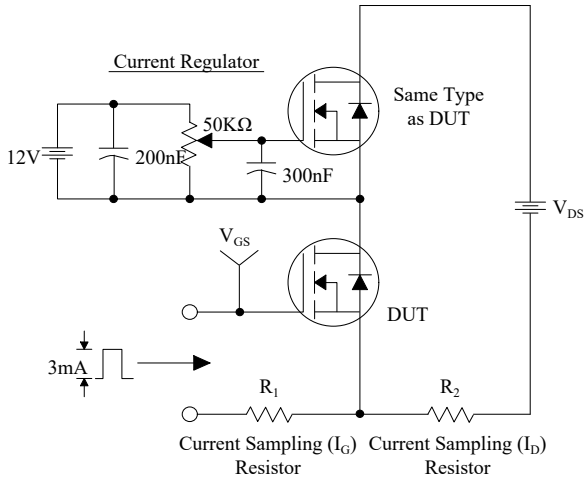
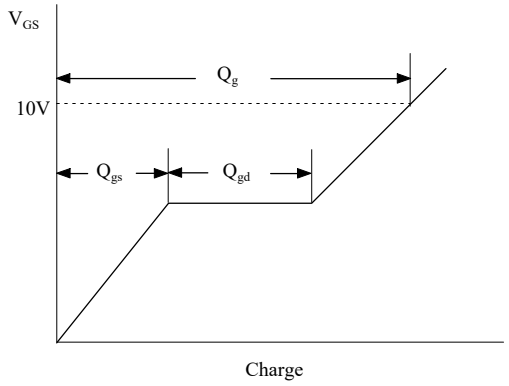


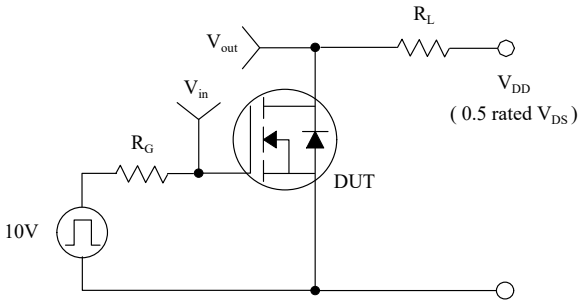
Figure 11. Transient Thermal Response Curve

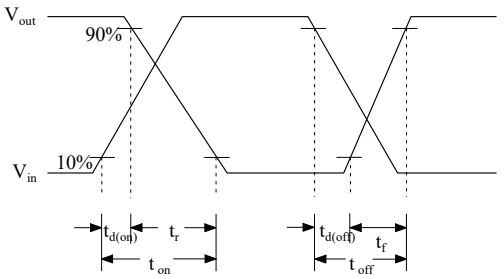
Gate Charge Test Circuit & Waveform



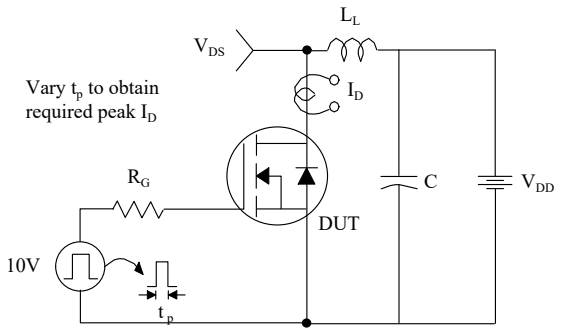


Resistive Switching Test Circuit & Waveforms

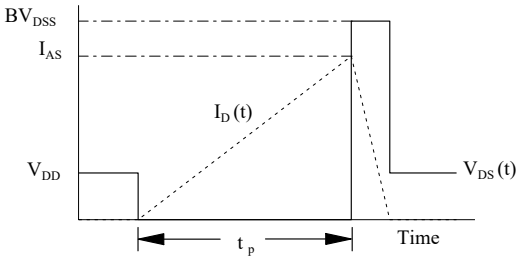




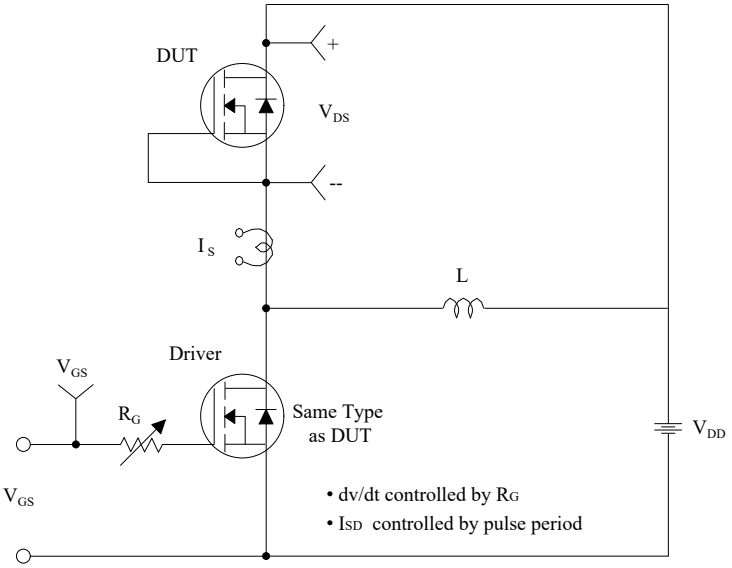
Unclamped Inductive Switching Test Circuit & Waveforms

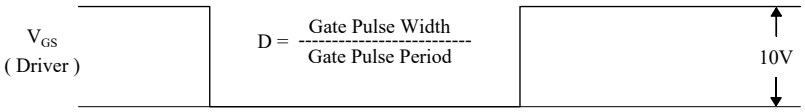


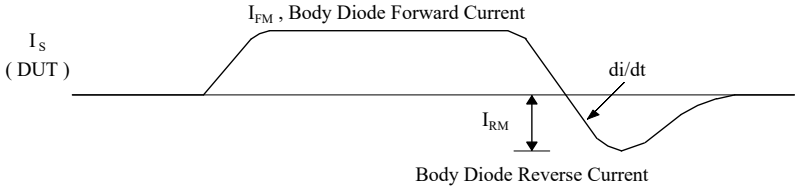
$$E_{AS} = \frac{1}{2} L_L I_{AS}^2 \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

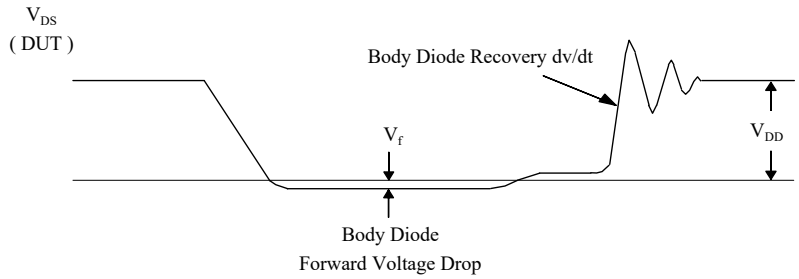


Peak Diode Recovery dv/dt Test Circuit & Waveforms

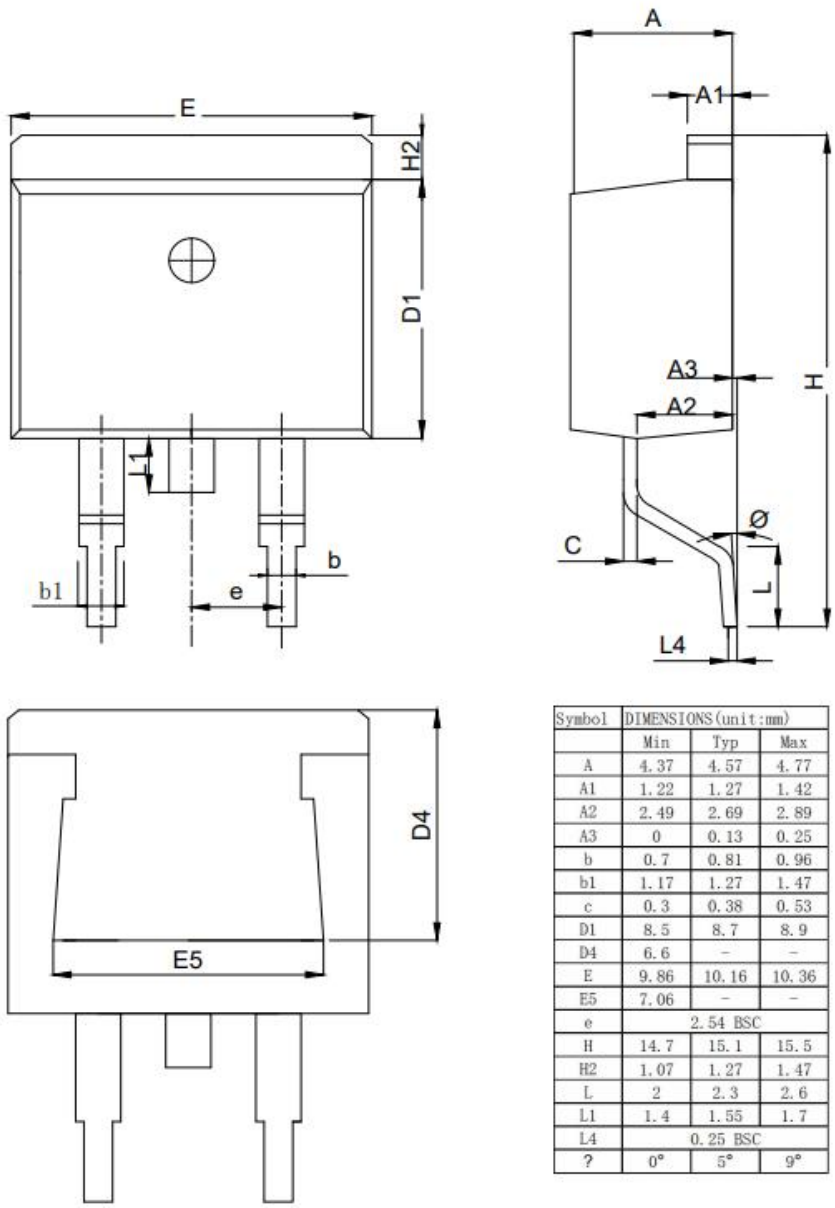








TO-263 OUTLINE



Symbol	DIMENSIONS(unit:mm)		
	Min	Typ	Max
A	4.37	4.57	4.77
A1	1.22	1.27	1.42
A2	2.49	2.69	2.89
A3	0	0.13	0.25
b	0.7	0.81	0.96
b1	1.17	1.27	1.47
c	0.3	0.38	0.53
D1	8.5	8.7	8.9
D4	6.6	–	–
E	9.86	10.16	10.36
E5	7.06	–	–
e	2.54 BSC		
H	14.7	15.1	15.5
H2	1.07	1.27	1.47
L	2	2.3	2.6
L1	1.4	1.55	1.7
L4	0.25 BSC		
?	0°	5°	9°

NOTE：
1The plastic package is not marked as smooth surfaceRa=0.1;Subglossy surfaceRa=0.8
2.Undeclared tolerance±0.25,Unmarked filletRmax=0.25

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